

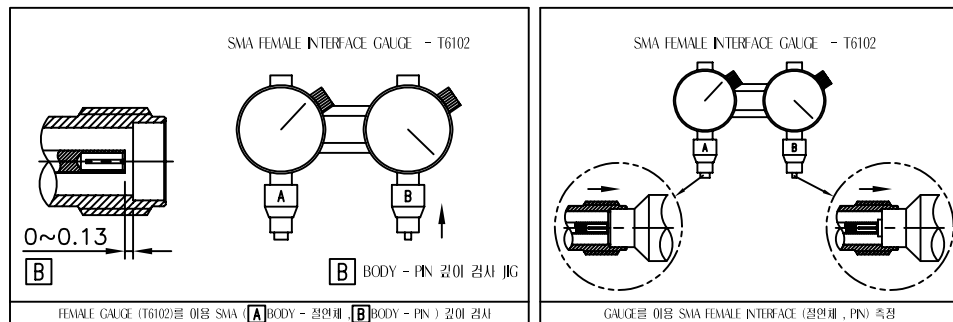
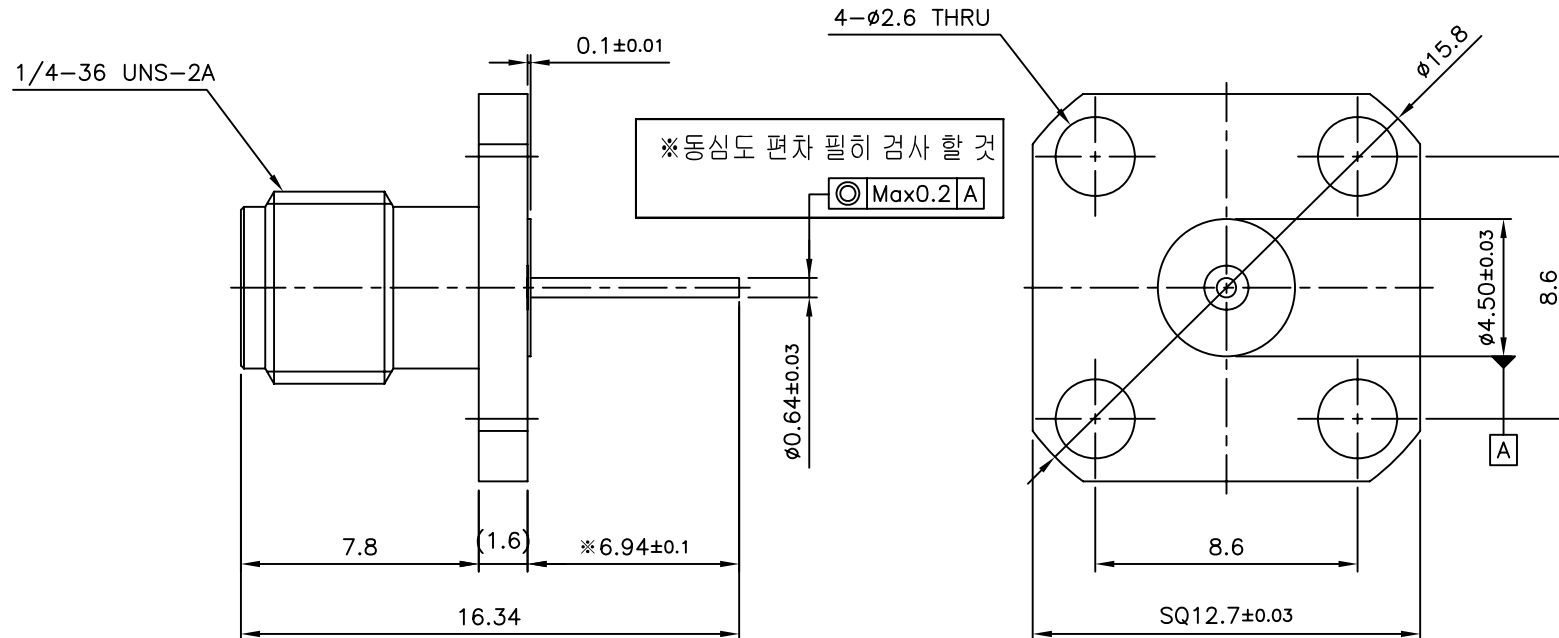
Mate compatible table	
SMA [~18GHz]	Mate
3.5mm [~26.5GHz]	
2.92mm(K) [~40GHz]	
2.4mm [~50GHz]	Mate
1.85mm(V) [~65GHz]	

Un mate

REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2018.09.18.
1	핀 돌출 전장 길이 및 조립 후 형 발생 개선건	S.Y.EUN	I.C.KIM	2019.01.04.

ELECTRICAL DATA

1. IMPEDANCE : 50ohm
2. FREQUENCY RANGE : DC~40GHz
3. VSWR (Max) : 1.2



** PIN 높이 검사 방법 **

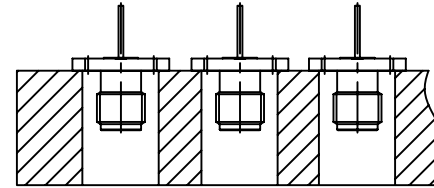
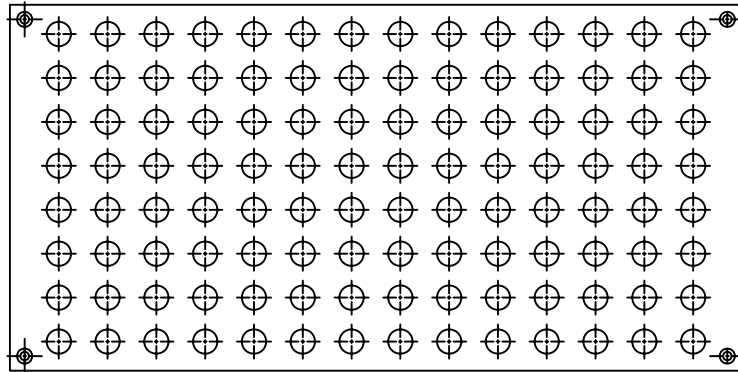
4	포장금형 GASKET	1	NBR	BLACK	DGK00335-N/1
3	INSULATOR	1	TEFLON		DIN02928-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT03864-5/1
1	BODY	1	SUS	Passivated	DBD04342-5/3
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2019. 01. 04.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM		
	±0.2				
MATERIAL	±1°	CHECKED BY	TITLE 2.92mm SOLDER END JS-4H		

FINISH	_____	DRAWN BY	A4		
	_____	S.Y.EUN			
		SCALE	UNIT	DWG NO. CN03716-7/4	
		4/1	mm		
				SHEET 1 of 1	

1) 조립 시 주의사항

- 커넥터 조립 후 DEQ00580-N/1 조립 트레이 사용하여 올려둘 것 (조립 후 핀 휨 방지)

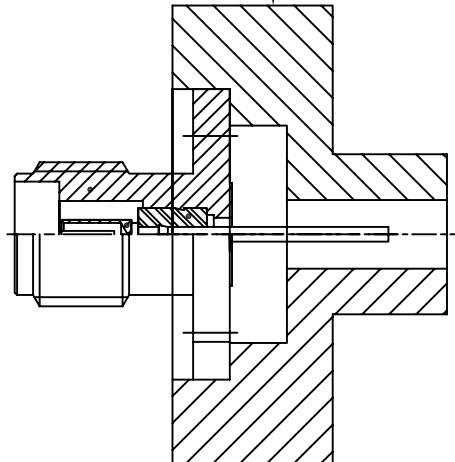


2) 포장사양

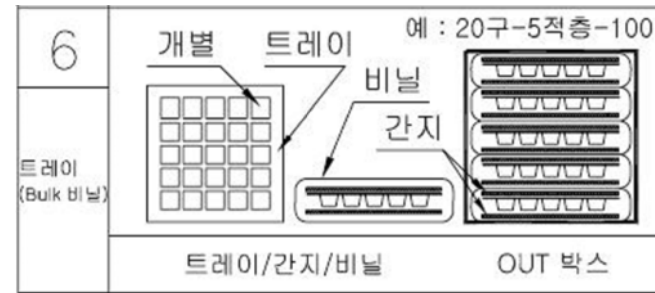
- 포장 시 고무금형(DGK00335-N/1)에 조립할 것

고무금형 (DGK00335-N/1)

NBR (BLACK)



포장 1안) 트레이 포장



: Tray 100구 + 위/아래 간지 → 박스 포장

포장 2안) 비닐 개별포장

